

MOSFETs Silicon P-Channel MOS (U-MOSVI)

# SSM3J340R

# 1. Applications

· Power Management Switches

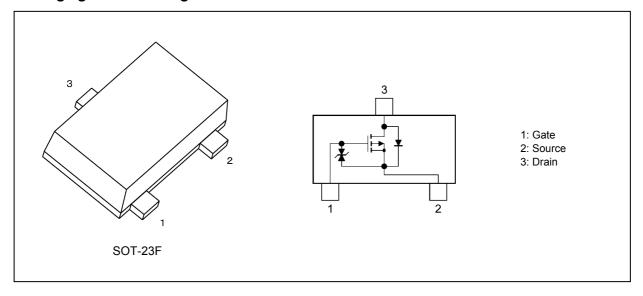
### 2. Features

- (1) 4.0-V drive
- (2) Low drain-source on-resistance
  - $: R_{DS(ON)} = 86 \text{ m}\Omega \text{ (max) } (@V_{GS} = -4.0 \text{ V})$

 $R_{\rm DS(ON)}$  = 73 m $\Omega$  (max) (@V<sub>GS</sub> = -4.5 V)

 $R_{\mathrm{DS(ON)}} = 45~\mathrm{m}\Omega~(\mathrm{max})~(@V_{\mathrm{GS}} = \text{-}10~\mathrm{V})$ 

### 3. Packaging and Pin Assignment





# 4. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

	Characteristics			Symbol	Rating	Unit
Drain-source voltage				$V_{DSS}$	-30	V
Gate-source voltage	,			$V_{GSS}$	-25 / +20	
Drain current (DC)			(Note 1)	Ι <sub>D</sub>	-4	Α
Drain current (pulsed)			(Note 1), (Note 2)	$I_{DP}$	-12	
Power dissipation	,		(Note 3)	$P_D$	1	W
Power dissipation		t ≤ 10 s	(Note 3)	P <sub>D</sub>	2	
Channel temperature				T <sub>ch</sub>	150	°C
Storage temperature	,			T <sub>stg</sub>	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- Note 1: Ensure that the channel temperature does not exceed 150 °C.
- Note 2: Repetitive rating; pulse width limited by maximum channel temperature.
- Note 3: Device mounted on a 25.4 mm × 25.4 mm × 1.6 mm FR4 glass epoxy board (Cu pad: 645 mm<sup>2</sup>)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance, R<sub>th(ch-a)</sub>, and the drain power dissipation, P<sub>D</sub>, vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.



#### 5. Electrical Characteristics

## 5.1. Static Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

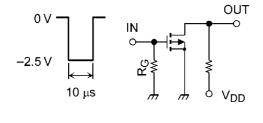
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 16 \text{ V}$	_	_	±1	μА
Drain cut-off current		I <sub>DSS</sub>	V <sub>DS</sub> = -30 V, V <sub>GS</sub> = 0 V	_	_	-1	
Drain-source breakdown voltage		V <sub>(BR)DSS</sub>	$I_D = -250 \mu A, V_{GS} = 0 V$	-30	_		V
Gate threshold voltage		$V_{th}$	$V_{DS} = V_{GS}$ , $I_{D} = -250 \mu A$	-1.0	_	-2.2	
Drain-source on-resistance	(Note 1)	R <sub>DS(ON)</sub>	$I_D = -1.0 \text{ A}, V_{GS} = -4.0 \text{ V}$	_	61	86	mΩ
			I <sub>D</sub> = -4.0 A, V <sub>GS</sub> = -4.5 V	_	55	73	
			I <sub>D</sub> = -4.0 A, V <sub>GS</sub> = -10 V	_	35	45	
Forward transfer admittance	(Note 1)	Y <sub>fs</sub>	$V_{DS}$ = -10 V, $I_{D}$ = -2.0 A	_	7.1	_	S

Note 1: Pulse measurement.

# 5.2. Dynamic Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V,	_	492	_	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1 MHz	_	75		
Output capacitance	C <sub>oss</sub>		_	97	_	
Switching time (turn-on time)	t <sub>on</sub>	$V_{DS} = -15 \text{ V}, I_D = -2 \text{ A},$	_	65	_	ns
Switching time (turn-off time)	t <sub>off</sub>	$V_{GS}$ = 0 to -4.5 V, $R_{G}$ = 10 $\Omega$	_	93		

### 5.3. Switching Time Test Circuit



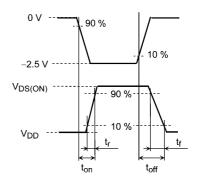


Fig. 5.3.1 Switching Time Test Circuit

Fig. 5.3.2 Input Waveform/Output Waveform

# 5.4. Gate Charge Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)		$V_{DD} = -15 \text{ V}, I_{D} = -4.0 \text{ A},$	_	6.2	_	nC
Gate-source charge 1	Q <sub>gs1</sub>	$V_{GS} = -4.5 \text{ V}$	_	1.5	_	
Gate-drain charge	Q <sub>gd</sub>		_	2.8	_	

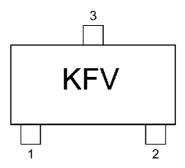
## 5.5. Source-Drain Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage	(Note 1)	$V_{DSF}$	I <sub>D</sub> = 4.0 A, V <sub>GS</sub> = 0 V	_	0.85	1.1	V

Note 1: Pulse measurement.



# 6. Marking



Rev.3.0



### 7. Characteristics Curves (Note)

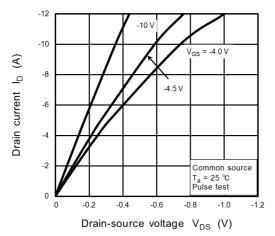


Fig. 7.1 I<sub>D</sub> - V<sub>DS</sub>

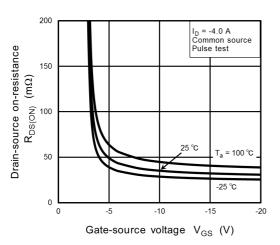


Fig. 7.3 R<sub>DS(ON)</sub> - V<sub>GS</sub>

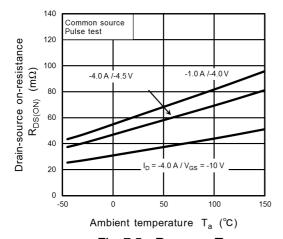


Fig. 7.5  $R_{DS(ON)}$  -  $T_a$ 

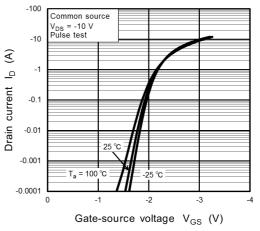


Fig. 7.2 I<sub>D</sub> - V<sub>GS</sub>

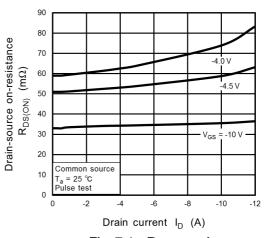


Fig. 7.4 R<sub>DS(ON)</sub> - I<sub>D</sub>

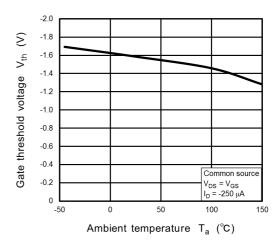
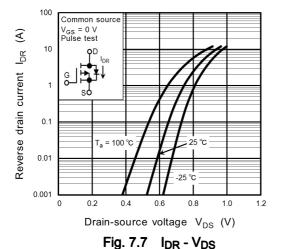
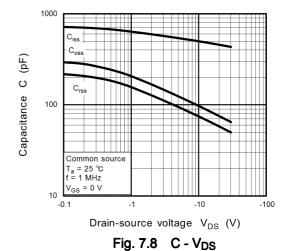
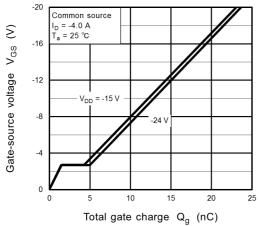


Fig. 7.6 V<sub>th</sub> - T<sub>a</sub>









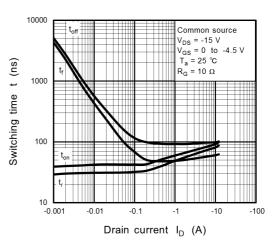
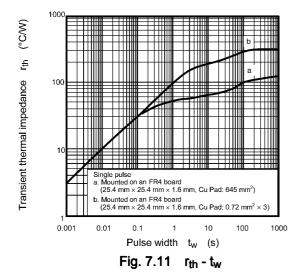


Fig. 7.9 Dynamic Input Characteristics





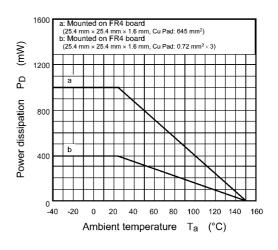


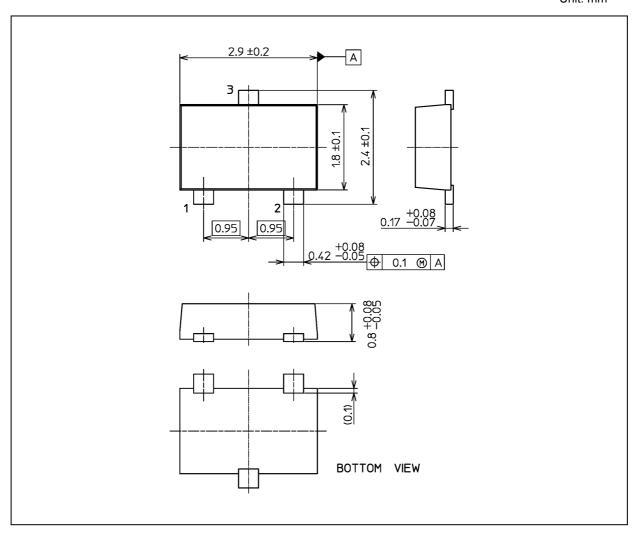
Fig. 7.12 P<sub>D</sub> - T<sub>a</sub>

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



## **Package Dimensions**

Unit: mm



Weight: 0.011 g (typ.)

	Package Name(s)
Nickname: SOT-23F	

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